

Amendments to the Specification

Please amend the specification as follows.

Please amend the paragraph beginning at page 11, line 18, as follows:

Camera 17—~~grounded~~ placed above supply table 11 takes an image of semiconductor element 2 adhered to adhesive sheet 12. An image taken with camera 17 undergoes recognition processing at semiconductor recognition unit 20 to recognize a position of semiconductor element 2 in adhesive sheet 12. A result of position recognition is sent to control unit 21 and as well to semiconductor separating mechanism driver 14. Control unit 21, based on the result of position recognition, controls mounting head actuator 19, and thereby, when mounting head 16 picks up semiconductor element 2, suction nozzle 8 and ejector pin unit 13a are aligned with semiconductor element 2 that is a target of picking up.